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| Form PTO-1449 (Modified) | ATTY DOCKET NO. B-3752DIV 619413-2 | U.S. SERIAL NO. Not yet assigned |
|---|---|---|
| LIST OF PATENTS AND PUBLICATIONS STATEMENT | APPLICANT Daniel Yap, et al. | |
| | FILING DATE concurrently herewith | GROUP unknown |

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| EXAMINER INITIAL | | DOCUMENT NUMBER | ISSUE DATE | NAME | CLASS | SUB-CLASS | FILING DATE or 102(e) DATE IF APPROPRIATE |
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| EXAMINER | DATE CONSIDERED |
|---|---|
| LUAN THAI | 3/03 |

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.